

At page 2, line 5, after "below", please insert the following: --as shown in Figure 2a--.

At page 4, line 3, please replace "the" with --a--.

At page 4, line 3, please replace "layer" with --plug--.

At page 12, line 1, after the word "deposited", please delete the word "over" and insert the following: --onto the polishing pad. The polishing pad then contacts a metal layer on--.

At page 16, line 2, please replace the phrase "layer over" with the following: --plug on--.

At page 16, line 4, please replace the second occurrence of the word "layer" with the following: --plug--.

At page 16, line 5, please replace the word "layer" with the following: --plug--.

IN THE FIGURES

Applicants have amended **Figure 11**. Applicants respectfully request the Examiner's approval of the amendments to this figure.

IN THE CLAIMS

Please amend the claims as follows:

- Sub B1
1. (Amended) A method of removing a particle from a metal [layer over a substrate] surface of a via comprising:
 - [depositing] introducing a first agent [onto the substrate] to a metal layer;
 - polishing the metal layer with the first agent; and